

MODULE HAVING DUAL-BAND SURFACE ACOUSTIC WAVE
CIRCUITS AND METHOD OF MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

A module that contains multiple surface acoustic wave (SAW) circuits and a method of manufacturing the module. In one embodiment, the module includes: (1) a hermetically-sealable shell having first and second terminal sets, (2) a first SAW circuit, located within the shell and couplable to the first terminal set, that filters signals in a first band of communications frequencies, and (3) a second SAW circuit, located within the shell and couplable to the second terminal set, that filters signals in a second band of communications frequencies.